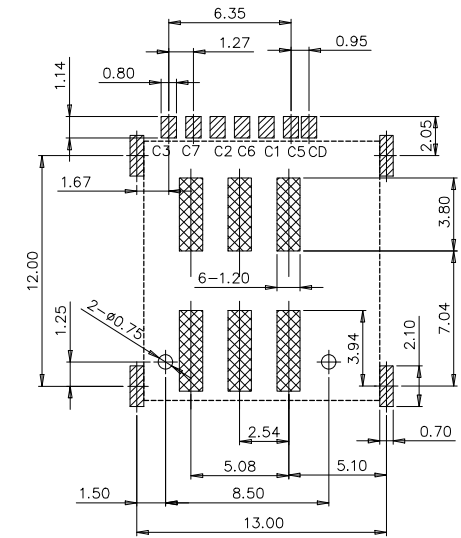
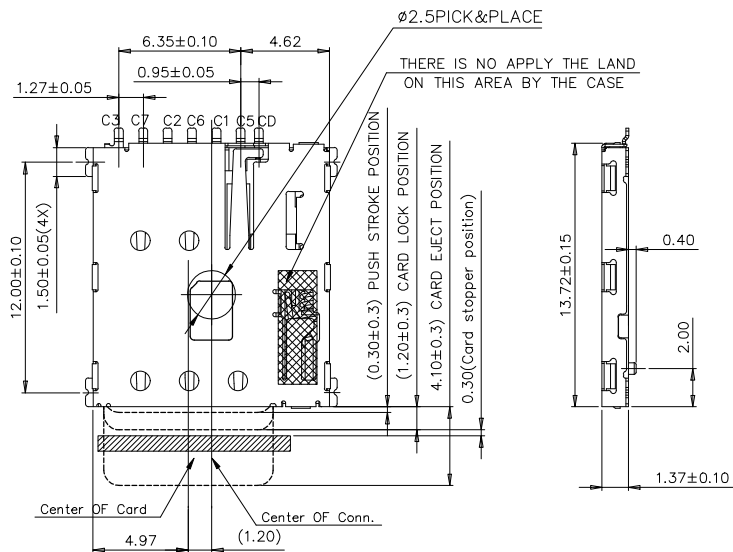
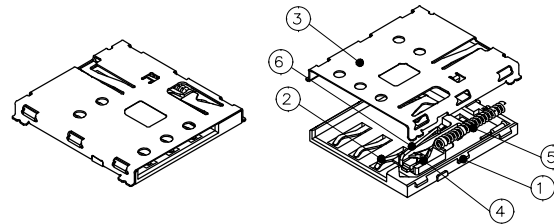
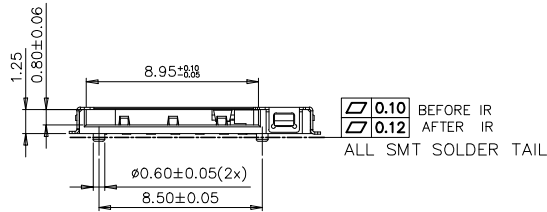




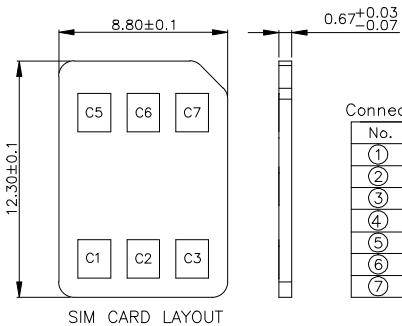
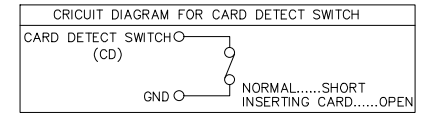
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED METAL MASK T=0.12MM



THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES
SMT SOLDER AREA



Connector Pin Assignment

No.	Pin Name	Description
①	C1	Vcc of SIM
②	C2	RST of SIM
③	C3	CLK of SIM
④	C5	GND of SIM
⑤	C6	Vpp of SIM
⑥	C7	I/O of SIM
⑦	SW	Detection Switch

NOTES:

- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:50mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260+0/-5s 30±10s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition: Temperature-40C~+85°C
Humidity 80% R.H MAX

ITEM	DESCRIPTION	MATERIAL	FINISH	Q'TY
⑥	HOOK	SUS304	NO PLATING	1
⑤	SPRING	SUS	NO PLATING	1
④	SLIDE	PA46	GLASS FILLED(OR EQUAL), UL 94V-0, BLACK	1
③	SHELL	STAINLESS STEEL	GOLD FLASH PLATED ON SOLDER TAIL AREA. NICKEL 30~100u" UNDER PLATED OVER ALL	1
②	TERMINAL	COPPER ALLOY	GOLD FLASH PLATED ON CONTACT AREA"A" SEE "PLATED CODE NOTE" NICKEL 50~150u" UNDER PLATED OVER ALL	1
①	HOUSING	LCP	GLASS FILLED(OR EQUAL), UL 94V-0, BLACK	1

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.5 X.X :±0.20 X.XX :±0.10
ANGLES: X :±2° X.X :±1°



TITLE	6Pin 1.37H PUSH PUSH Nano SIM CARD CONN.		
DWN	xiong	PART NO. SNO-1351	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1

CUSTOMER COPY